Title (en)

GLASS FIBER-REINFORCED PREPREGS, LAMINATES, ELECTRONIC CIRCUIT BOARDS AND METHODS FOR ASSEMBLING A FABRIC

Title (de)

GLASFASERVERSTÄRKTE PREPREGS, LAMINATE, ELEKTRISCHE LEITERPLATTE UND VERFAHREN ZUR HERSTELLUNG EINES GEWEBES

Title (fr)

PLAQUETTES DE CIRCUITS ELECTRONIQUES, STRATIFIES ET FEUILLES PREIMPREGNEES RENFORCES PAR FIBRES DE VERRE, ET PROCEDE D'ASSEMBLAGE D'UN TISSU

Publication

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Application

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Abstract (en)

[origin: WO0021900A1] One aspect of the present invention is a prepreg for an electronic support, the prepreg comprising: (a) a polymeric matrix material; and (b) a fabric comprising a strand comprising glass fibers, at least a portion of the fabric having a coating which is compatible with the polymeric matrix material, the prepreg having a drill tip percent wear of no greater than about 32 percent, as determined after drilling 2000 holes through a stack of 3 laminates, each laminate including eight of the prepregs, at a hole density of 62 holes per square centimeter (400 holes per square inch) and a chip load of 0.001 with a 0.46 mm (0.018 inch) diameter tungsten carbide drill. The present invention also provides a laminate incorporating the prepreg. Another aspect of the present invention is a prepreg for an electronic support, the prepreg comprising: (a) a polymeric matrix material; and (b) a woven reinforcement fabric comprising glass fibers, at least a portion of the fabric having a coating which is compatible with the polymeric matrix material, the prepreg having a deviation distance of no greater than about 36 micrometers, as determined after drilling 2000 holes through a stack of 3 laminates at a hole density of 62 holes per square centimeter (400 holes per square inch) and a chip load of 0.001 with a 0.46 mm (0.018 inch) diameter tungsten carbide drill. The present invention also provides a laminate incorporating the prepreg.

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